

# Orderable Parts for: MT29F512G08CMCEBJ4-37ITR

**SEE ALL MLC NAND PARTS** 

	Status	Media	FBGA Code	SPD Data	Chipset Validation	PLP	Start Date	Alternative Part
MT29F512G08CMCEBJ4- 37ITR:E	Production	N/A	NQ467	N/A	N/A	No		N/A

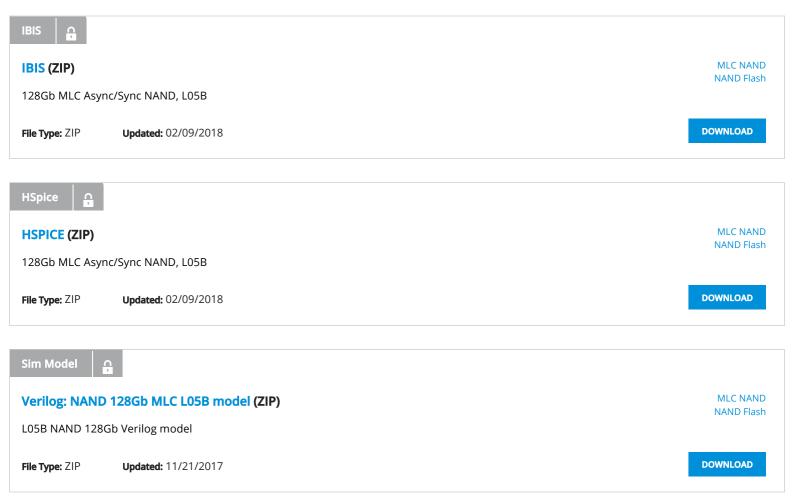
# **Detailed Specifications**

Density	512Gb	Status	Sampling	NAND Type	3D	Width	x8
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# Sim Models & Software

# Sim Models



# Software

### **Software Support Pack**

#### mtd-nand-use-a-lower-value-for-badblockbits-when-working-with-MLC-NAND (ZIP)

MLC NAND NAND Flash

MLC NANDs have more bit flips that SLC. When looking for bad block marker we have a lot of false positive if we check for the whole byte. To avoid this tolerate a few (4 here) bit flips for byte.

File Type: ZIP

**Updated:** 03/31/2016

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### Software Support Pack

## NAND FLASH lockunlock bug fix (ZIP)

MLC NAND NAND Flash SLC NAND

Reset NAND before write protect check.

Downloaded from Arrow.com.

File Type: ZIP Updated: 03/31/2016

**Software Support Pack** 

#### fixup-ubi-cannot-recover-master node issue (ZIP)

MLC NAND NAND Flash

For MLC NAND, paired page issue is now a common known issue. This patch is just for master node cannot be recovered while there will two pages be dameged in one single master block.

File Type: ZIP

**Updated:** 03/31/2016

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# Software Support Pack

## **UBI power loss issue for paired page Ver2.0 (ZIP)**

MLC NAND NAND Flash

These patches aim to solve MLC NAND paired page power loss issue by adding a bakvol (backup volume) module in UBI layer. 70 series and 80 series families.

File Type: ZIP

**Updated:** 03/31/2016

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#### **Software Support Pack**

#### YAFFS mark bad block issue (ZIP)

MLC NAND NAND Flash SLC NAND

If the bitflips num over mtd->bitflip\_threshold the mtd\_read\_oob will return -EUCLEAN and tags->ecc\_result > YAFFS\_ECC\_RESULT\_NO\_ERROR. Then we will call yaffs\_handle\_chunk\_error.

File Type: ZIP

**Updated:** 03/31/2016

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# **RoHS Certificates**

#### **RoHS Certificates**

## **RoHS Certificate of Compliance (PDF)**

Part-specific certification of how this product meets the requirements of the current DIRECTIVE 2011/65/EU and 2015/863/EU, a.k.a. Restriction of Hazardous Substances (RoHS) Directive (Recast) without exemptions.

File Type: (PDF)

**Updated:** 09/2018

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## **RoHS Certificates**

## China RoHS Certificate (PDF)

Part-specific certification as required by China's Management Methods for Controlling Pollution by Electronic Information Products.

File Type: (PDF)

**Updated:** 09/2018

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# Documentation & Support

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## **Technical Notes**

**SEARCH (4) MLC NAND TECHNICAL NOTES** 

### **Technical Notes**

### TN-00-33: Power Integrity Simulation with IBIS 5.0 Models (PDF)

(TN-00-33) This technical note describes the new features in IBIS 5.0 enabling PI simulation. It also provides an overview of some of the modeling accuracy challenges and compares SSO simulation results using various electronic design automation (EDA) software tools.

File Type: PDF

**Updated:** 01/25/2016

3D NAND DDR3 SDRAM DDR4 SDRAM DRAM See More Tags

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#### **Technical Notes**

#### TN-00-01: Moisture Sensitivity of Plastic Packages (PDF)

(TN-00-01) This technical note describes shipping procedures for preventing memory devices from absorbing moisture and recommendations for baking devices exposed to excessive moisture.

File Type: PDF

**Updated:** 02/14/2013

DDR SDRAM DDR2 SDRAM DDR3 SDRAM DDR3L-RS See More Tags

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# **Customer Service Notes**

**SEE ALL CUSTOMER SERVICE NOTES** 

### **Customer Service Note**

#### **Product Marks, Product Labels, and Packaging Labels (PDF)**

(CSN-11) The first section of this customer service note describes the product marks and labels we place on our devices. The second section describes the labels used on and in our packaging.

File Type: PDF

**Updated:** 08/24/2018

3D XPoint Client Cloud Cloud See More Tags

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## **Customer Service Note**

#### **Micron BGA Manufacturer's User Guide (PDF)**

DDR2 SDRAM DDR4 SDRAM Embedded USB eMMC See More Tags of high-level guidelines and a reference manual describing typical package-related and...

File Type: PDF

**Updated:** 12/10/2014

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# Parts with the same Data Sheet (2)

	608CMCEBJ4-37IT R Current )	MT29F128G08CBCEBJ4-37ITR	MT29F256G08CECEBJ4-37ITR
Status	Sampling	Sampling	Sampling
Density	512Gb	128Gb	256Gb
NAND Type	3D	3D	3D
Width	х8	x8	x8
Voltage	3.3V	3.3V	3.3V
Package	VBGA	VBGA	VBGA
Pin Count	132-ball	132-ball	132-ball
Op. Temp.	-40C to +85C	-40C to +85C	-40C to +85C
MT/s	533 MT/s	533 MT/s	533 MT/s
Pro	duct Name		

# MT29F512G08CMCEBJ4-37IT

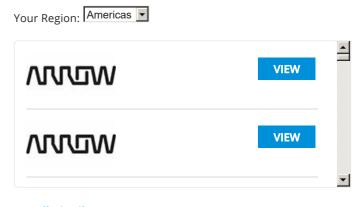
K

(Current)

Status	Sampling
Density	512Gb
NAND Type	3D
Width	<b>x8</b>
Voltage	3.3V
Package	VBGA
Pin Count	132-ball
Op. Temp.	-40C to +85C
MT/s	533 MT/s

# Where to Buy

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Managed NAND

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